



# LGAD Detectors at Electron Ion Collider

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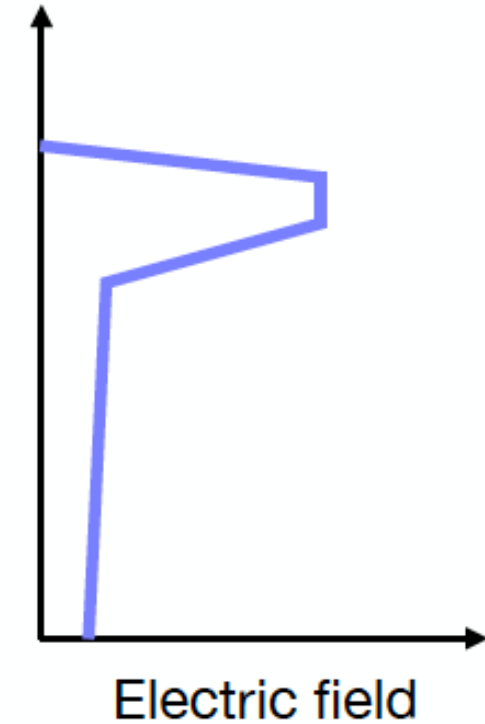
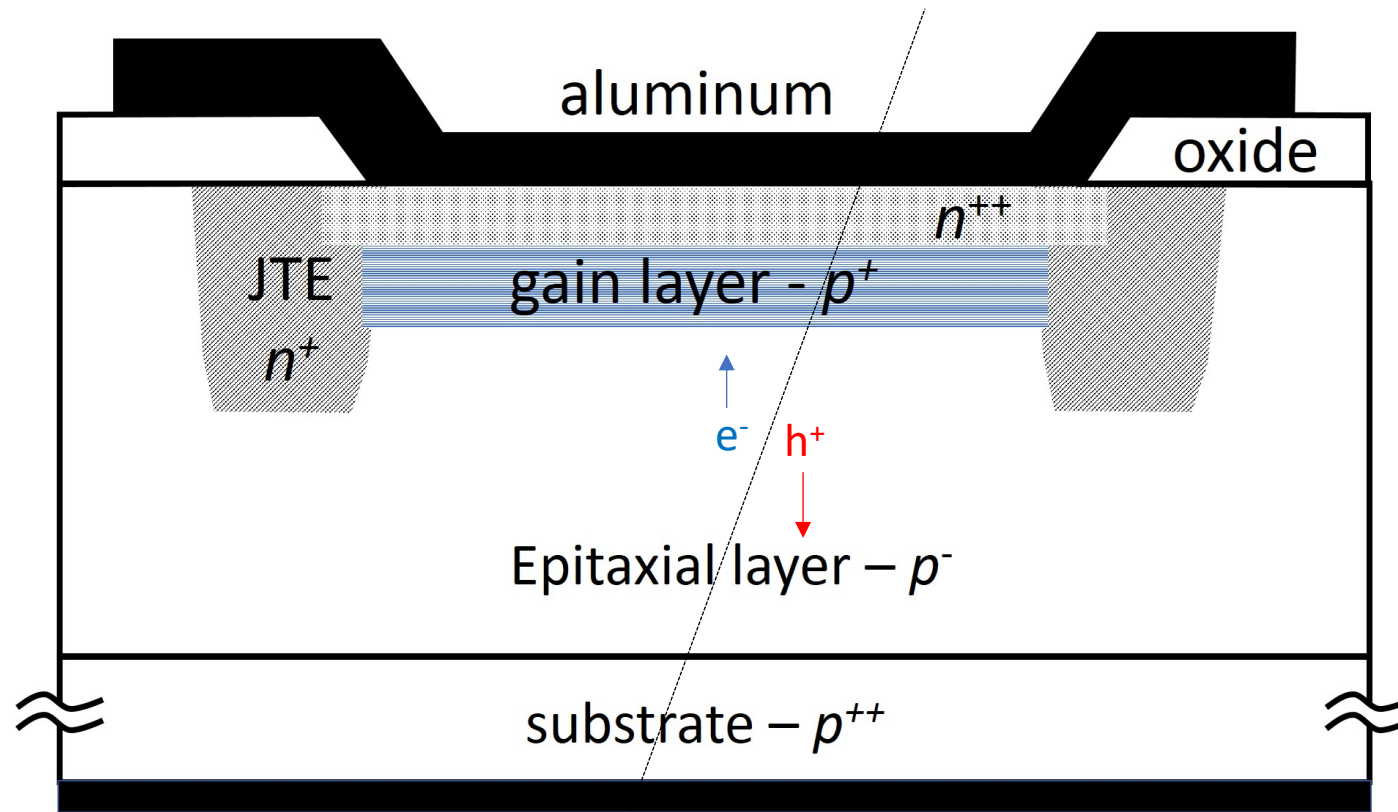
Electron-Ion Collider

**BROOKHAVEN**  
NATIONAL LABORATORY

Jefferson Lab

U.S. DEPARTMENT OF  
**ENERGY** | Office of  
Science

# Low Gain Avalanche Diode (LGAD)



Ultra-fast silicon detectors with a highly doped  $p^+$  gain layer  
Moderate internal gain : 10-30



# LGAD for CMS Phase-2 Upgrade

## Trigger/HLT/DAQ



- Track information in L1-Trigger
- L1-Trigger: 12.5 ms latency – output 750 kHz
- HLT output 7.5 kHz

## Barrel ECAL/HCAL



- Replace FE/BE electronics
- Lower ECAL operating temp. (8 °C)

## Muon Systems



- Replace DT & CSC FE/BE Electronics
- Complete RPC coverage in region  $1.5 < h < 2.4$
- Muon tagging  $2.4 < h < 3$

## New Endcap Calorimeters



- Rad. tolerant – high granularity
- 3D capable

## New Tracker

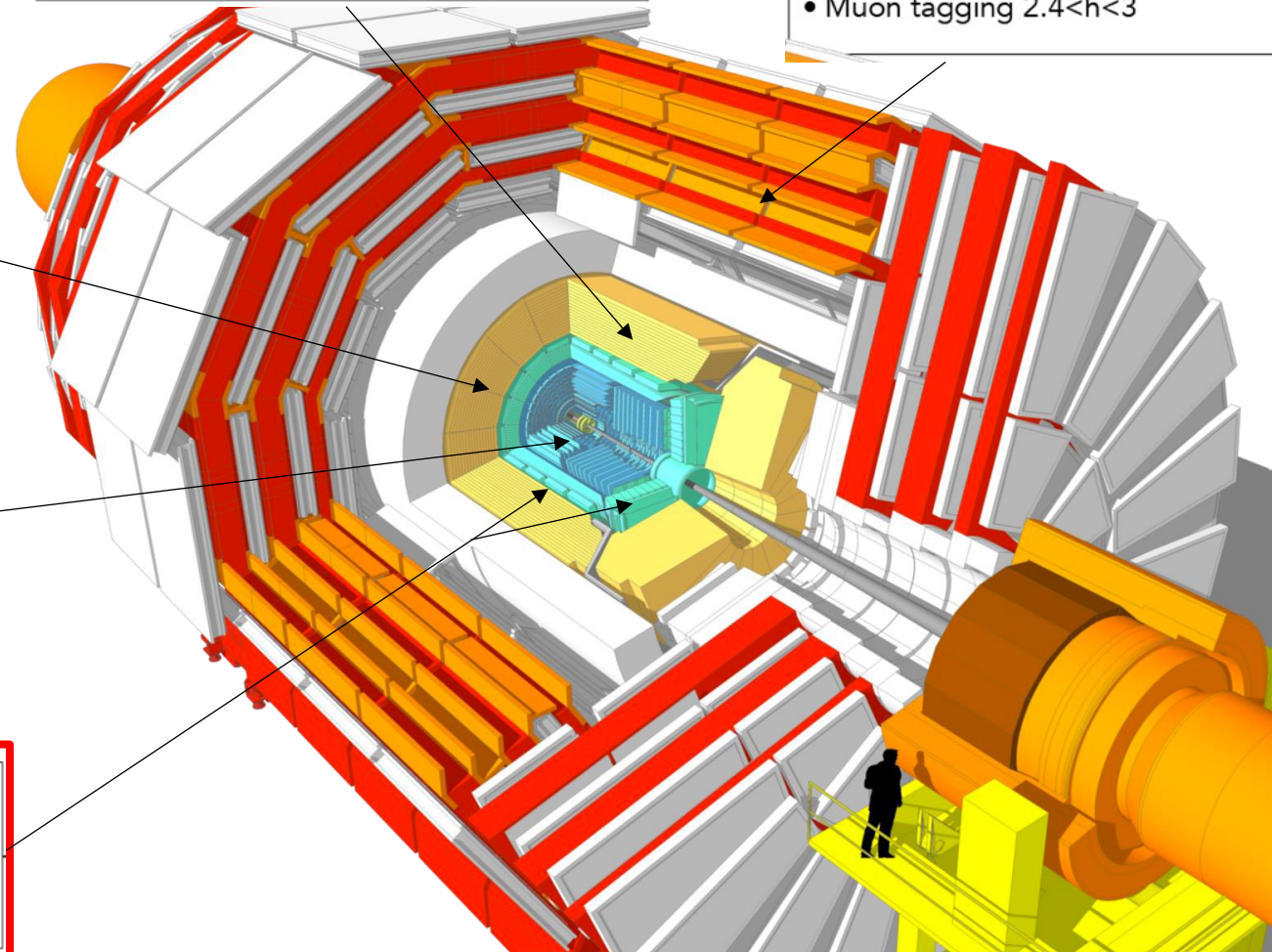


- Rad. tolerant – high granularity – significant less material
- 40 MHz selective readout ( $p_T > 2$  GeV) in Outer Tracker for L1 -Trigger
- Extended coverage to  $h=4$

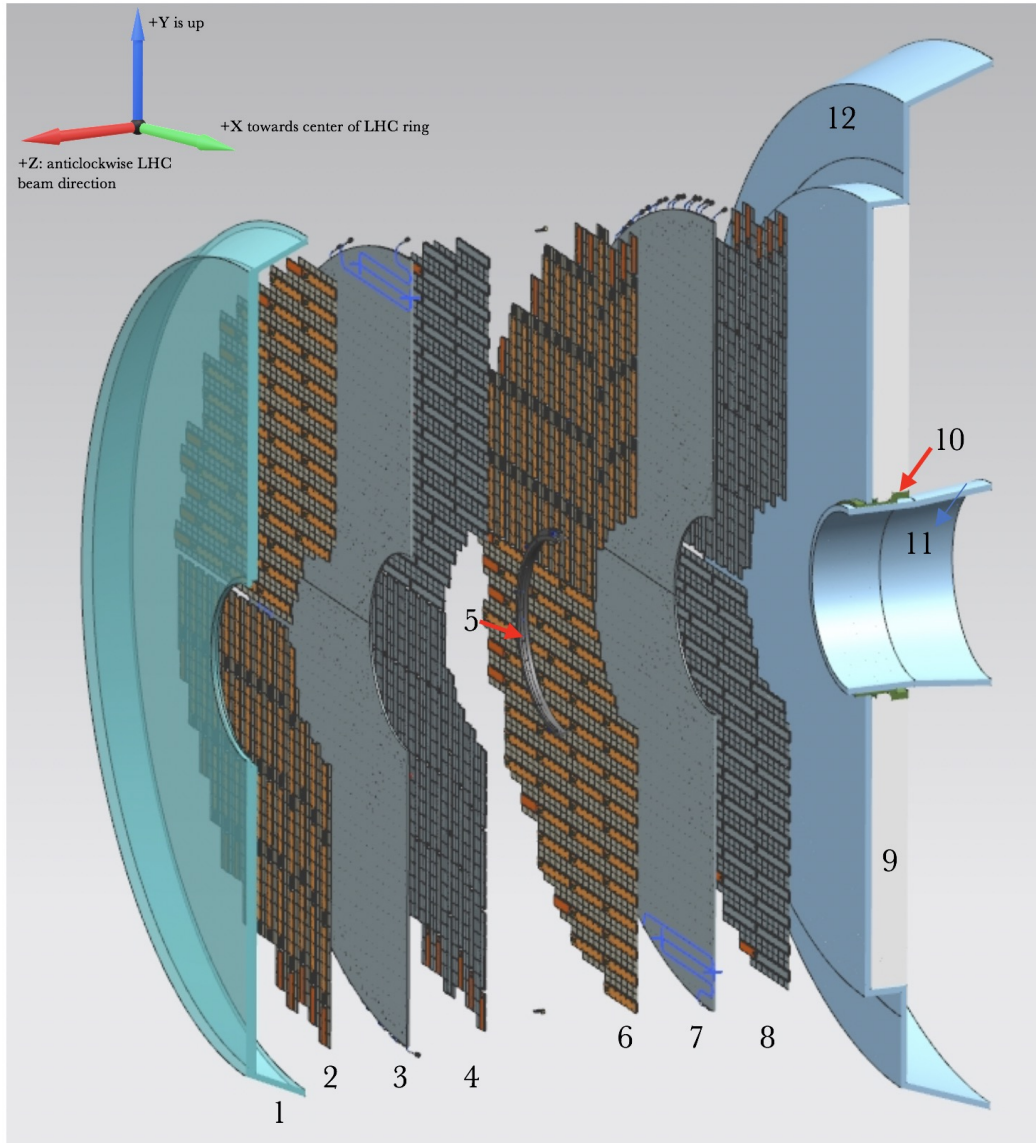


## MIP Precision Timing Detector

- Barrel: Crystal + SiPM
- Endcap: Low Gain Avalanche Diodes



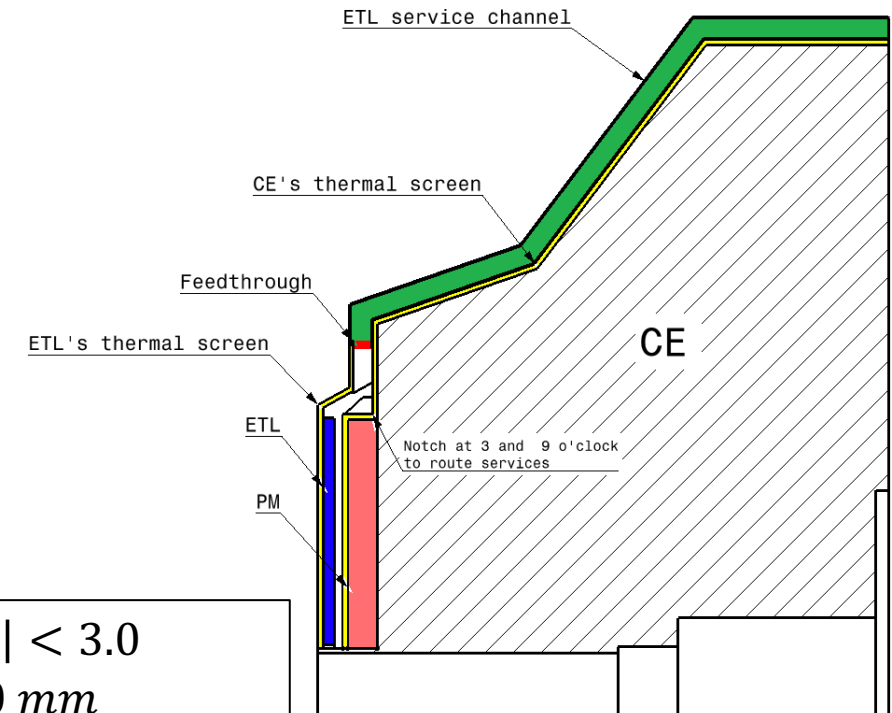
# CMS Endcap Timing Layer (ETL)



- 1: ETL Thermal Screen
- 2: Disk 1, Face 1
- 3: Disk 1 Support Plate
- 4: Disk 1, Face 2
- 5: ETL Mounting Bracket
- 6: Disk 2, Face 1
- 7: Disk 2 Support Plate
- 8: Disk 2, Face 2
- 9: HGCAL Neutron Moderator
- 10: ETL Support Cone
- 11: Support cone insulation
- 12: HGCAL Thermal Screen

- On the CE nose:  $1.6 < |\eta| < 3.0$
- Radius:  $315 < R < 1200 \text{ mm}$
- Position in Z:  $\pm 3.0 \text{ m}$  (45 mm thick)
- Surface  $\sim 15.8 \text{ m}^2$ ;  $\sim 8.6\text{M}$  channels
- Weight 282 kg/side; Power: 26kW/side

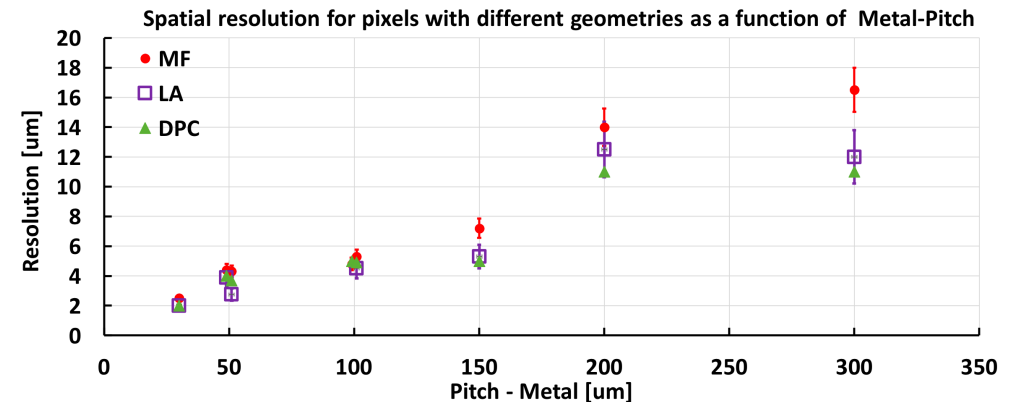
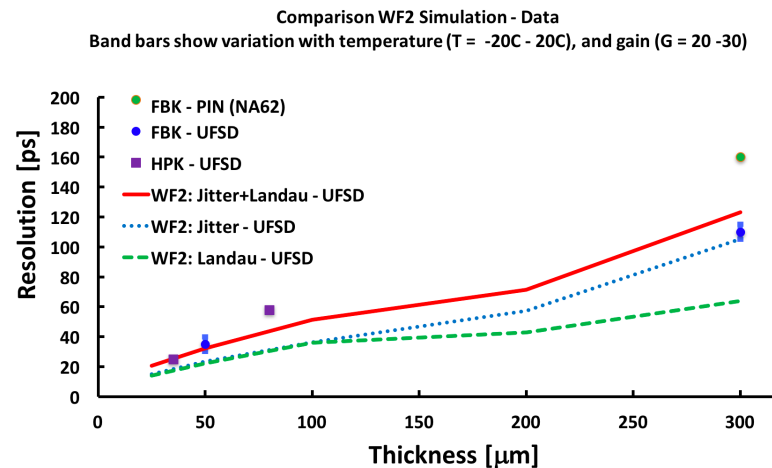
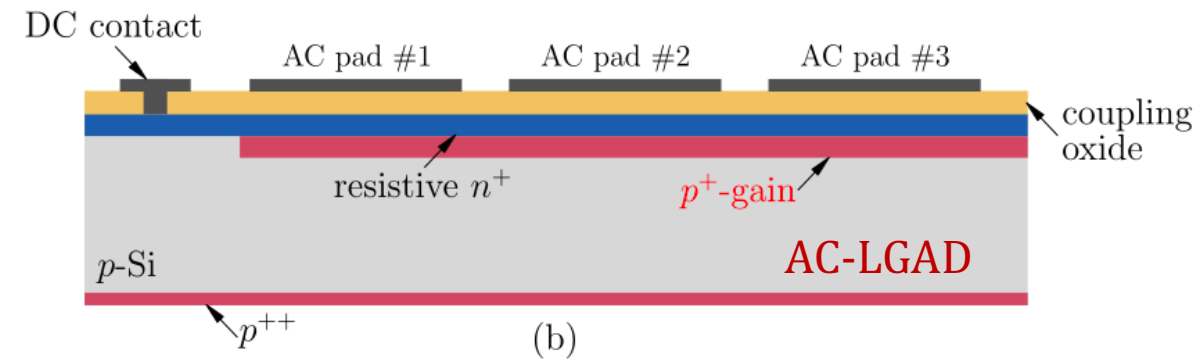
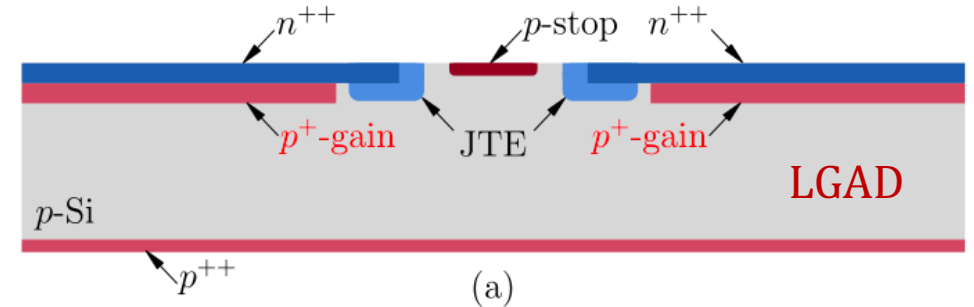
- **Two disks on each side allowing up to 2 time measurements per track**
  - **50 ps per hit  $\rightarrow$  30 ps per track**
- **Stageable, serviceable, maintainable**



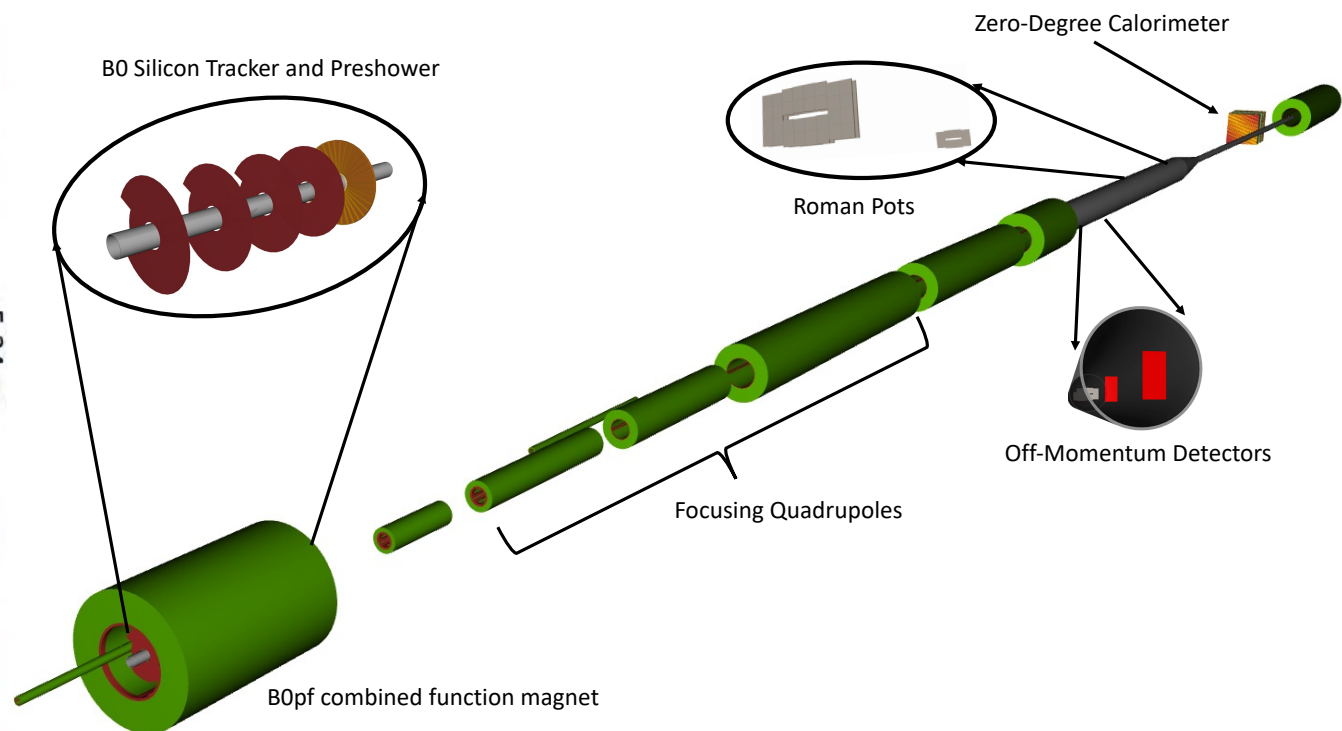
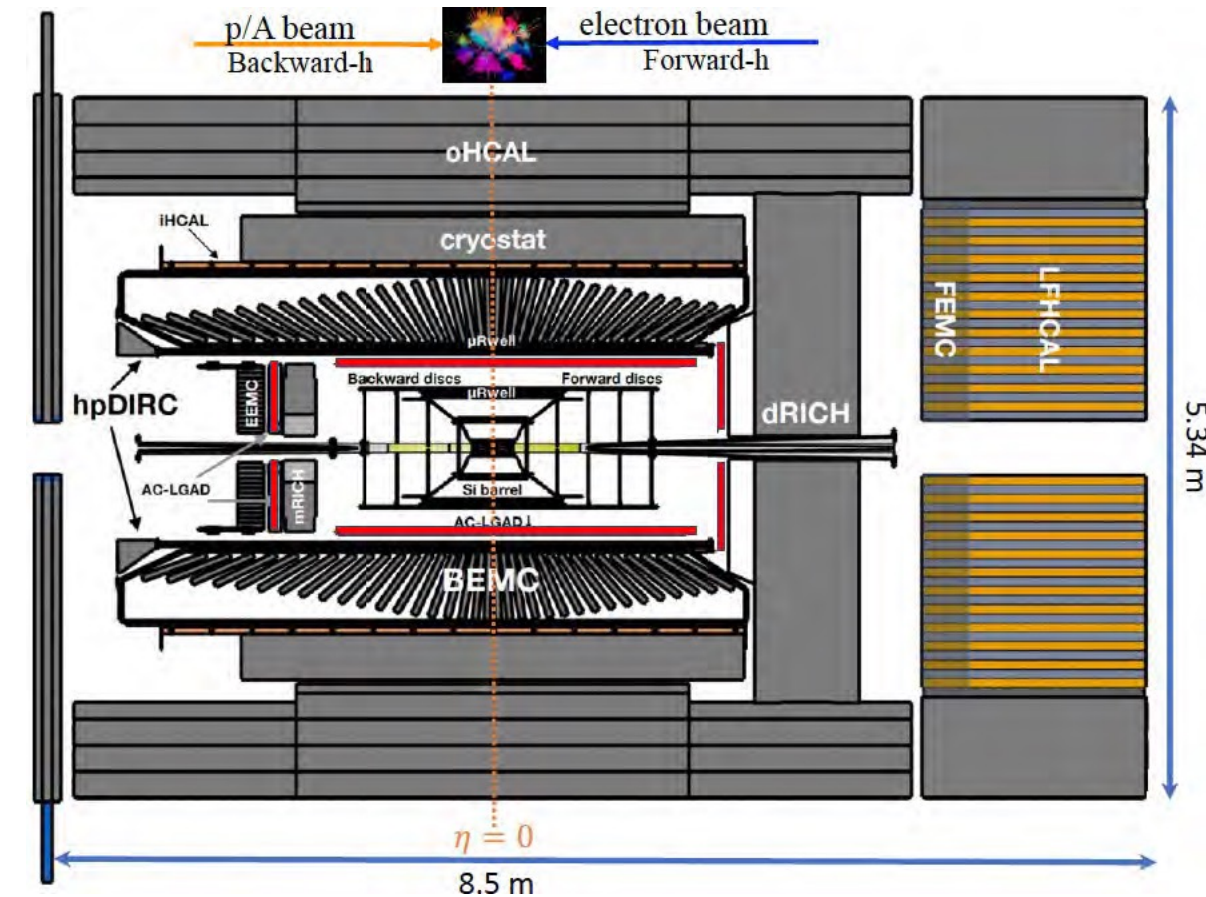


# AC-Coupled LGAD

- Due to the presence of JTE and the gap between LGAD cells, 100% fill factor can not be achieved in LGAD. The position resolution is limited to be  $\sqrt{1/12}$  of cell size.
- AC-LGAD: replacement of the segmented  $n^{++}$  layer by a less doped but continuous  $n^+$  layer. Electrical signals in the  $n^+$  layer are AC-coupled to neighboring metal electrodes that are separated from the  $n^+$  layer by a thin insulator layer.
- AC-LGAD can not only provide a timing resolution of a few tens of picoseconds, but also 100% fill factor and a spatial resolution that are orders of magnitude smaller than the cell size.



# AC-LGAD Detectors for ePIC



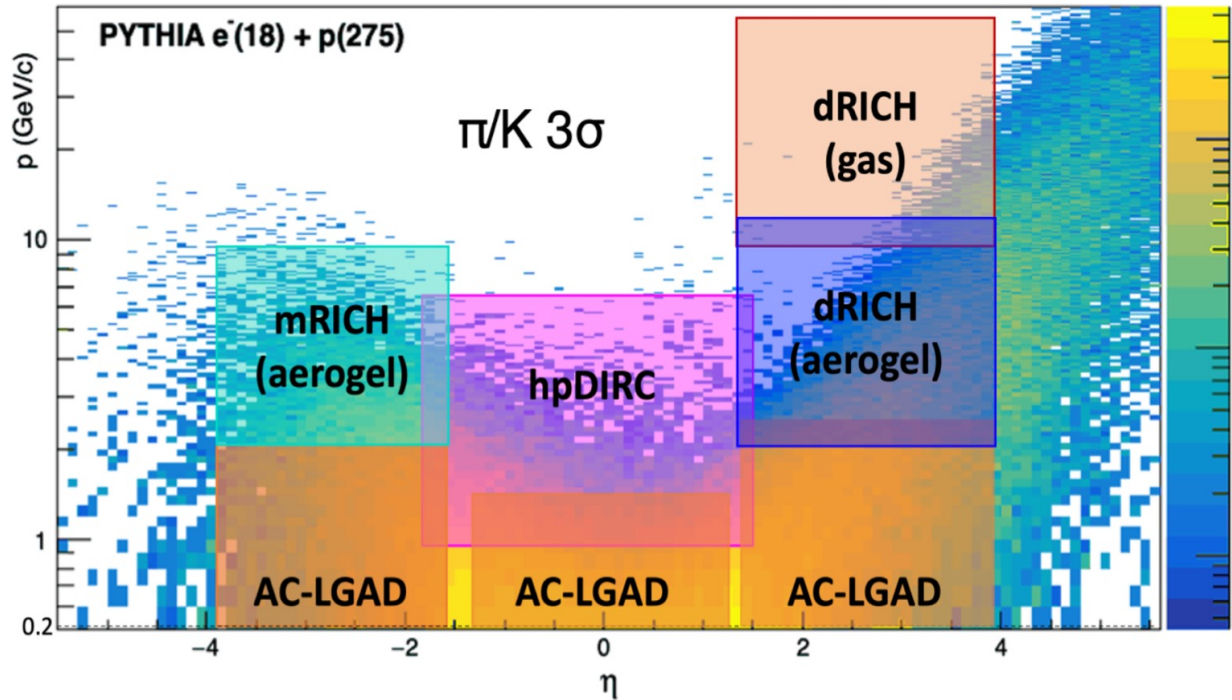
| Detector     | Angular accept.       | $p_T$ coverage         |
|--------------|-----------------------|------------------------|
| Backward ToF | $-3.7 < \eta < -1.74$ | $0.15 < p < 2.0$ GeV   |
| Barrel ToF   | $-1.4 < \eta < 1.4$   | $0.15 < p_T < 1.5$ GeV |
| Forward ToF  | $1.5 < \eta < 3.5$    | $0.15 < p < 2.0$ GeV   |

| Detector     | Angular accept.    | $p_T$ coverage                     |
|--------------|--------------------|------------------------------------|
| B0 Detector  | $4.6 < \eta < 5.9$ | Higher $p_T$                       |
| Roman Pots   | $\eta > 6$         | Low $p_T$ cut-off from beam optics |
| Off-Momentum | $\eta > 6$         | Low-rigidity from nucl. breakups   |

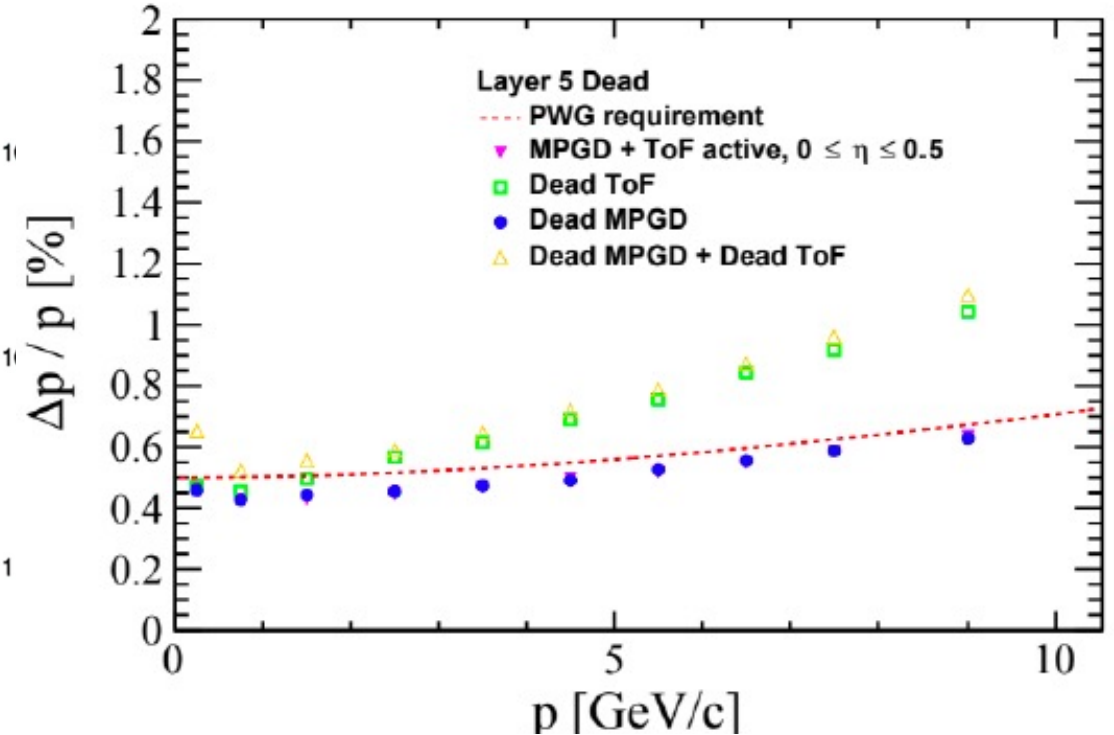


# AC-LGAD for Central Detector: TOF PID + Tracking

- Time-of-flight for e/ $\pi$ /K/p identification at low-to-intermediate momentum range
- Provide a high spatial resolution point for tracking



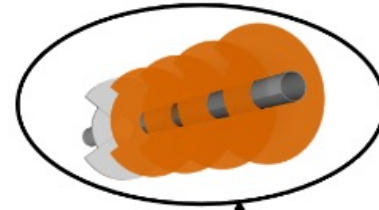
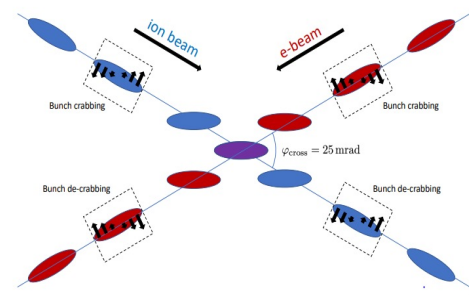
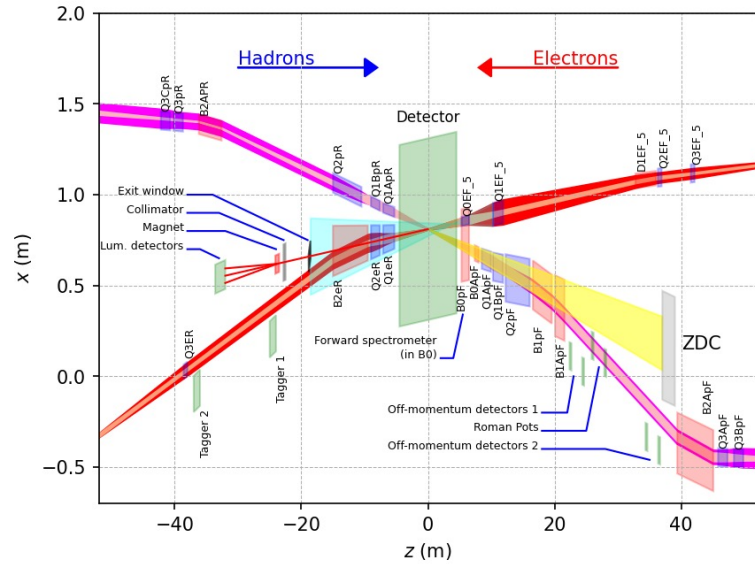
Missing hit in outer Si layer



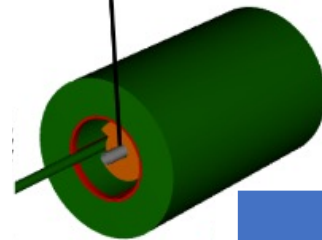
Need more than one technology to cover the entire momentum ranges at different rapidity

| Rapidity    | $\pi/K/p$ and $\pi^0/\gamma$ | e/h      | Min pT (E) |
|-------------|------------------------------|----------|------------|
| -3.5 – -1.0 | 7 GeV/c                      | 18 GeV/c | 100 MeV/c  |
| -1.0 – 1.0  | 8-10 GeV/c                   | 8 GeV/c  | 100 MeV/c  |
| 1.0 – 3.5   | 50 GeV/c                     | 20 GeV/c | 100 MeV/c  |

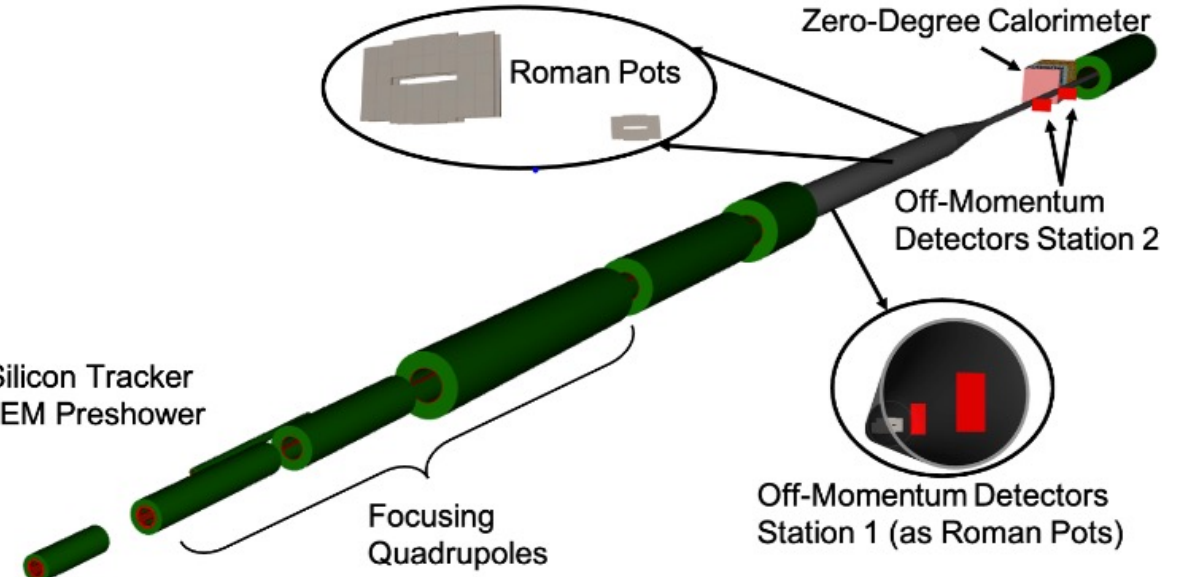
# AC-LGADs at Far-Forward: Timing + Tracking



B0 Silicon Tracker and EM Preshower

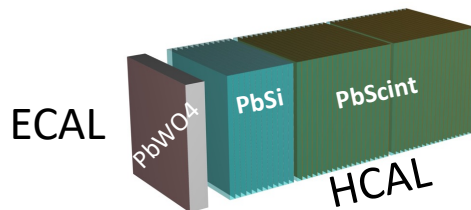


B0pf Dipole



## Technologies defined

- Silicon: AC-LGAD & MAPS
- ZDC:
  - ECAL (PbWO4)
  - HCAL (PbSi + PbScint)



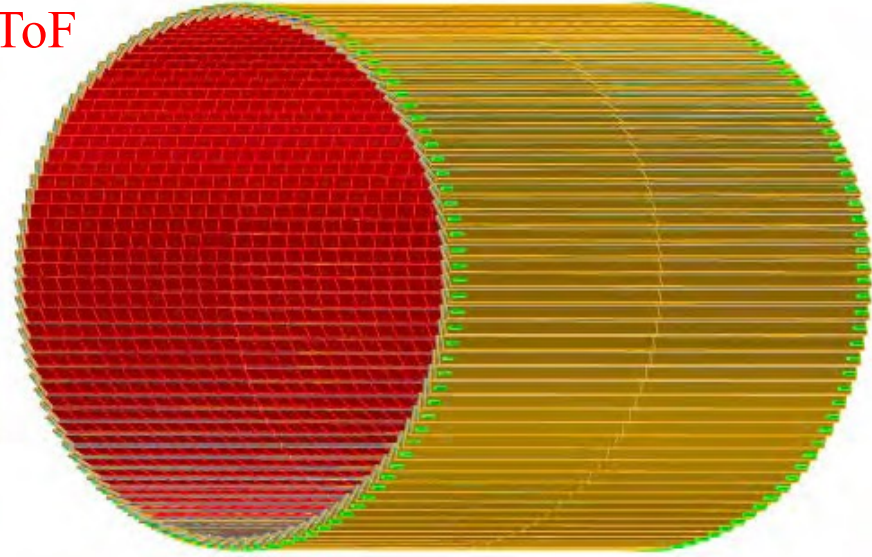
| Detector                | Angular accept. [mrad]                          | $p_T$ coverage                               |
|-------------------------|---|--|
| ZDC @ ~30m              | $\theta < 5.5$ ( $\eta > 6$ )                   | $p_T < 1.3$ GeV                              |
| Roman Pots              | $0 < \theta < 5.0$ ( $\eta > 6$ )               | *Low $p_T(t)$ cutoff (beam optics)           |
| Off-Momentum Detectors  | $0 < \theta < 5.0$ ( $\eta > 6$ )               | Low-rigidity particles from nuclear breakups |
| B0 forward spectrometer | $5.5 < \theta < 20.0$<br>( $4.6 < \eta < 5.9$ ) | High $p_T(t)$                                |



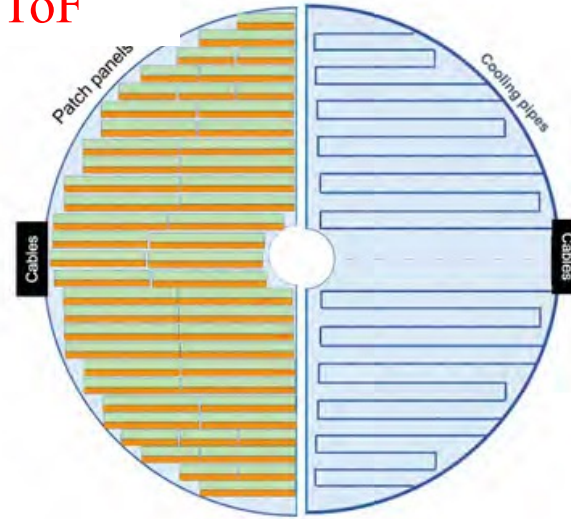
# Specifications of ePIC AC-LGAD Detectors

- High-level strawman layout design and requirements for sub-systems using AC LGADs.

BToF



FToF



Roman Pots



|             | Area (m <sup>2</sup> ) | Channel size (mm <sup>2</sup> ) | # of Channels | Timing Resolution | Spatial resolution                 | Material budget |
|-------------|------------------------|---------------------------------|---------------|-------------------|------------------------------------|-----------------|
| Barrel TOF  | 10.9                   | 0.5*10                          | 2.4M          | 30 ps             | 30 $\mu\text{m}$ in $r \cdot \phi$ | 0.01 X0         |
| Forward TOF | 2.22                   | 0.5*0.5                         | 8.8M          | 25 ps             | 30 $\mu\text{m}$ in x and y        | 0.08 X0         |
| B0 tracker  | 0.07                   | 0.5*0.5                         | 0.28M         | 30 ps             | 20 $\mu\text{m}$ in x and y        | 0.05 X0         |
| RPs/OMD     | 0.14/0.08              | 0.5*0.5                         | 0.56M/0.32M   | 30 ps             | 140 $\mu\text{m}$ in x and y       | no strict req.  |

Requirements on timing and spatial resolutions and material budget are still being evaluated and are subject to change as the design matures, and we will continue to explore common designs for these detectors where possible to reduce cost and risk.

# Questions to be Addressed

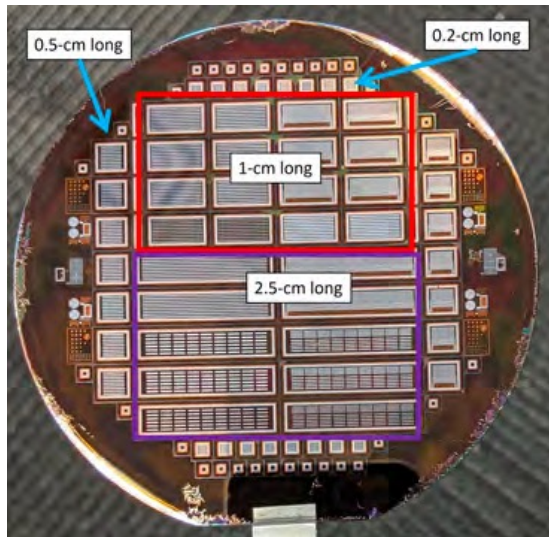
- **AC-LGAD sensor:**
  - Goal: large area sensors that meet timing/spatial resolution requirements with minimal # channels
  - Approach: utilize BNL IO to optimize the sensor design (pitch, electrode width, n-layer doping density, active volume thickness); engage commercial vendors to verify sensor quality and production cost/yield
- **Frontend readout ASIC:**
  - Goal: low jitter (15-20ps) and low power ( $\sim 1$  mW/channel), streaming readout with TDC and ADC outputs
  - Approach: custom-designed EICROC and FCFD, ASICs from 3rd party institutions
- **Sensor/ASIC integration**
  - Goal: reliable and cost-effective way to establish connections between AC-LGAD sensor and frontend ASIC
  - Approach: bump-bonding, wire-bonding, interposer
- **Mechanical structure with cooling:**
  - Goal: light-weight structure with cooling that meet the material budget, thermal and mechanical requirements
  - Approach: finite element analysis and prototyping with carbon-fiber composite and PEEK materials
- **Flex and frontend electronics:**
  - Goal: low jitter clock to frontend ASICs ( $< 5$  ps), low  $X_0$  flexible PCB to route power/signal to sensor/ASIC
  - Approach: design a precise clock distribution system in concert with EPIC DAQ group, design and prototype flexible PCB that meet the requirements; work with EPIC DAQ to define the streaming readout scheme



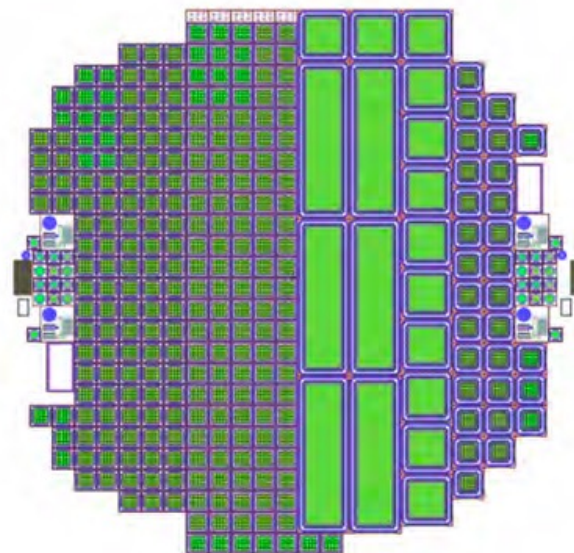
# AC-LGAD Sensor R&D

- Production of medium/large area sensors with different doping concentration, pitch and gap sizes between electrodes to optimize performance by BNL IO.
- Start production of sensors of small thickness (20 and 30 microns) for ToF applications with time resolution 20 ps.
  - 1<sup>st</sup> BNL IO (11/2021): 5-25 mm strips with 500  $\mu\text{m}$  pitch, 100-300  $\mu\text{m}$  electrode width, 50  $\mu\text{m}$  active Si
  - 2<sup>nd</sup> BNL IO (12/2022): 5-25 mm strips with 500-700  $\mu\text{m}$  pitch, 50-100  $\mu\text{m}$  electrode width, 20-50  $\mu\text{m}$  Si
  - 3<sup>rd</sup> BNL IO (03/2023): pixels with 500  $\mu\text{m}$  pitch, 20-50  $\mu\text{m}$  Si
  - Joint HPK production with KEK (4/2023): strip and pixel sensors with different pitch, electrode width, active Si thickness and n<sup>+</sup>-layer doping

1<sup>st</sup>/2<sup>nd</sup> BNL Production

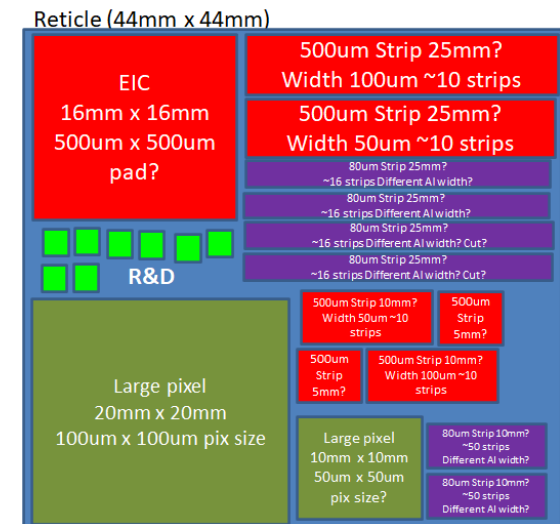


3<sup>rd</sup> BNL Production



eRD112

Joint HPK Production



# AC-LGAD Sensor R&D

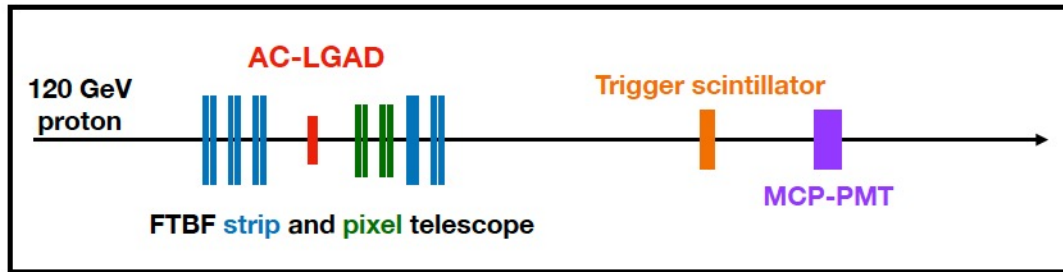
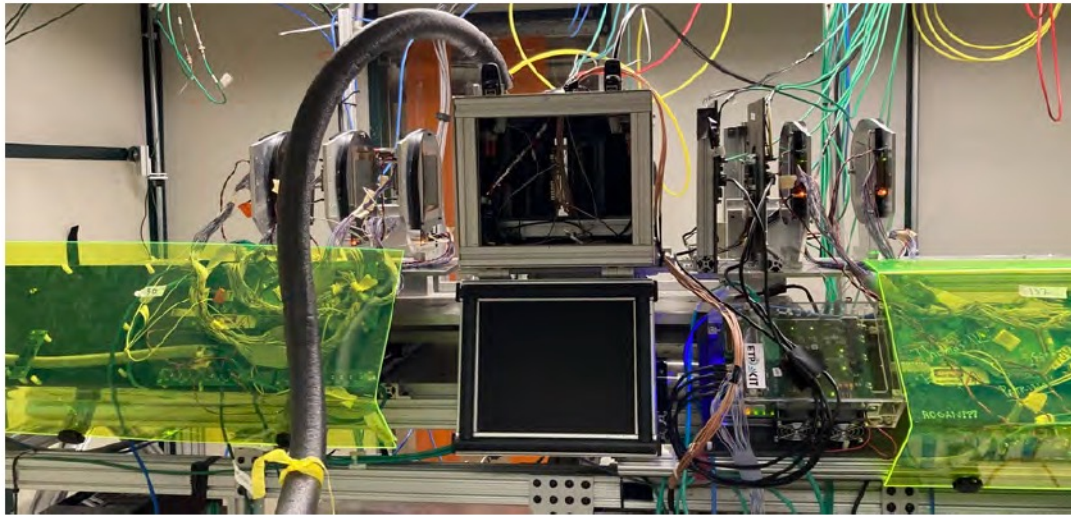


Figure 7: Picture (top) and diagram (bottom) of the FTBF silicon telescope and reference instruments used to characterize AC-LGAD performance. The telescope comprises five pairs of orthogonal strip layers and two pairs of pixel layers, for a total of up to 14 hits per track.

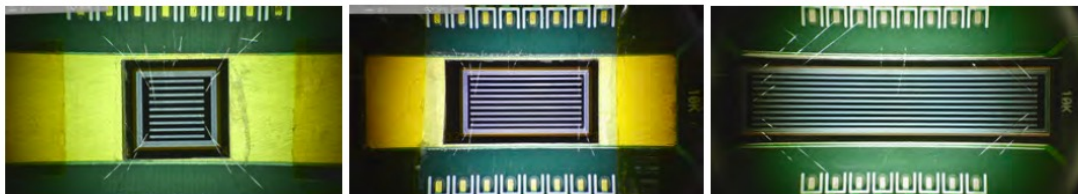
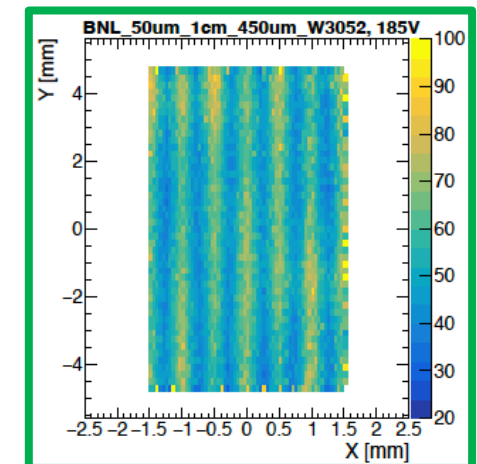
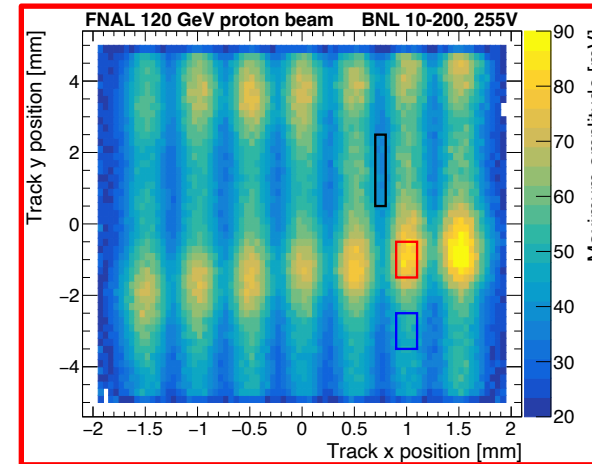


Figure 8: Three AC-LGAD strip sensors wire-bonded on Fermilab test board and tested at FTBF: BNL 5-200 (left), BNL 10-200 (middle) and BNL 25-200 (right). See text for details.



| Name       | Time resolution |               | Exactly one strip        |            | Two strip                |            |
|------------|-----------------|---------------|--------------------------|------------|--------------------------|------------|
|            | Overall ps      | Hot region ps | Resolution $\mu\text{m}$ | Fraction - | Resolution $\mu\text{m}$ | Fraction - |
| BNL 5-200  | $35 \pm 1$      | $30 \pm 1$    | $52 \pm 1$               | 35%        | $12 \pm 1$               | 65%        |
| BNL 10-100 | $42 \pm 1$      | $35 \pm 1$    | $28 \pm 1$               | 23%        | $19 \pm 1$               | 77%        |
| BNL 10-200 | $42 \pm 1$      | $32 \pm 1$    | $55 \pm 1$               | 43%        | $18 \pm 1$               | 57%        |
| BNL 10-300 | $40 \pm 1$      | $36 \pm 1$    | $78 \pm 1$               | 51%        | $16 \pm 1$               | 49%        |
| BNL 25-200 | $72 \pm 1$      | $51 \pm 1$    | $71 \pm 1$               | 82%        | $31 \pm 1$               | 18%        |

Table 4: Test beam results of AC-LGAD strip sensors from the first batch of BNL production.

- Timing and spatial resolutions of 1 cm long strip sensors from 1<sup>st</sup> BNL production are comparable to those of  $500 \times 500 \mu\text{m}^2$  pixel sensors from HPK ( $\sim 30$  ps,  $25 \mu\text{m}$ ), making strip sensors a promising candidate for EIC applications.
- Non-uniform gain in 1<sup>st</sup> BNL production sensors has been greatly improved in 2<sup>nd</sup> BNL production.

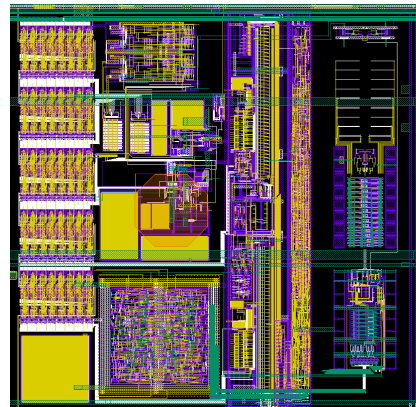


# Frontend ASIC R&D

A first ASIC prototype that is compatible with EIC Roman Pot requirements and can read out an AC-LGAD with 500 micron pitch and 20 ps time resolution.

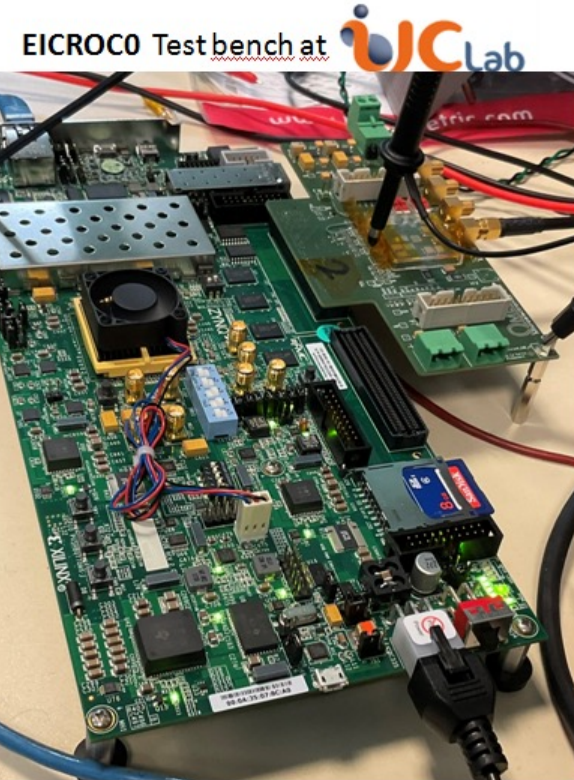
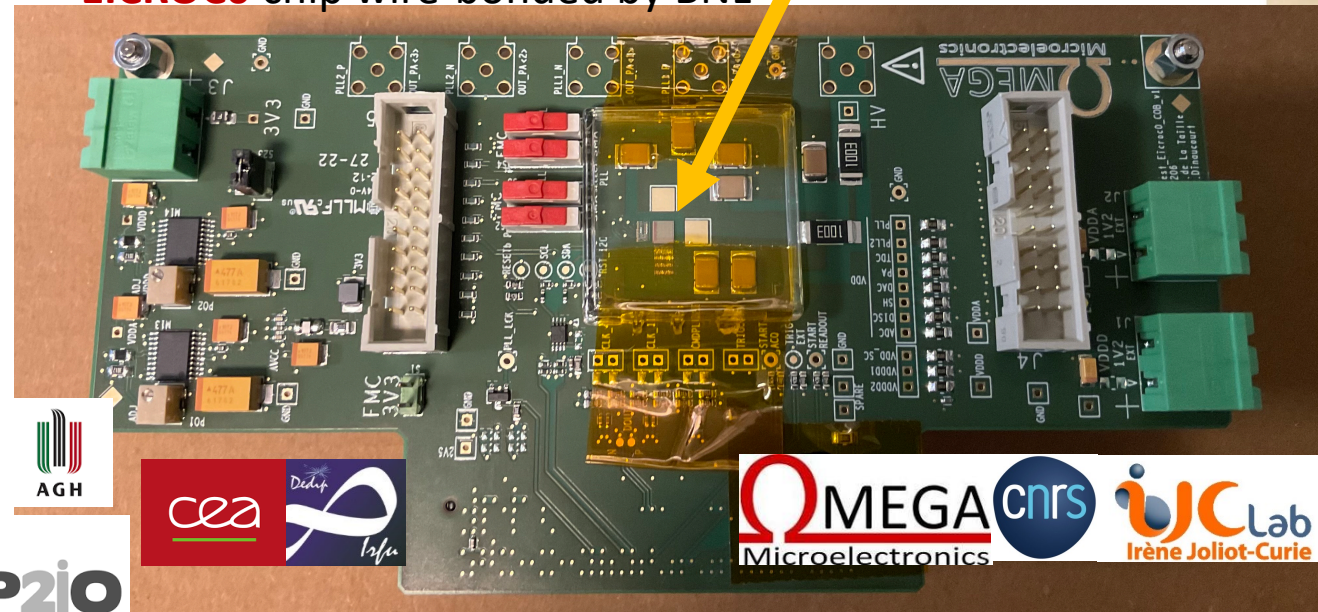
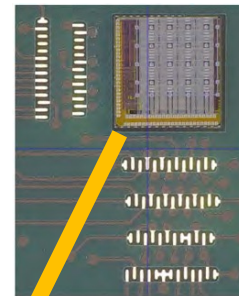
**EICROC0 (submitted in 3/2022, received in 7/2022) by OMEGA/CEA-Irfu/AGH/IJCLab**

- 4 x 4 channels with 500x500  $\mu\text{m}^2$  pitch
- Preamp, discri. taken from ATLAS ALTIROC
- I2C slow control taken from CMS HGCROC
- TDC (TOA) adapted by CEA-Saclay/Irfu
- ADC (40 MHz) adapted to 8bits by AGH Krakow
- Digital readout: FIFO depth8 (200 ns)



**EICROC0,**  
1 channel  
implantation

**EICROC0** chip wire-bonded by BNL

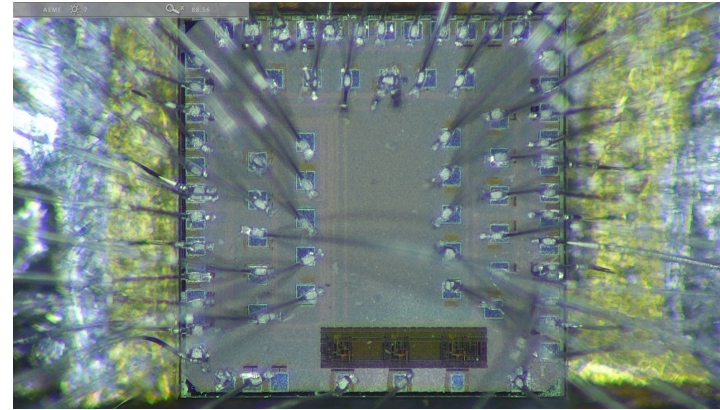




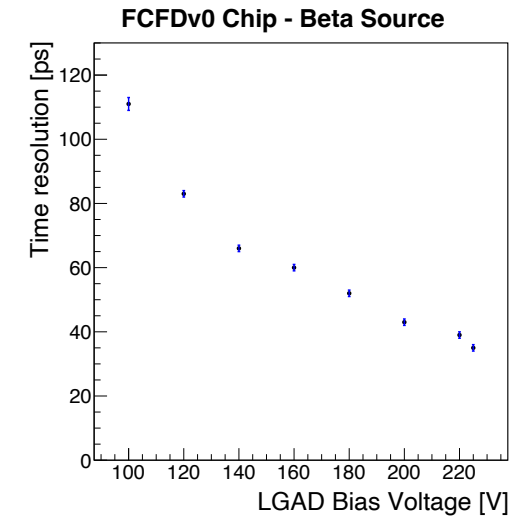
# Frontend ASIC R&D

## FCFDv0 (Fermilab CFD v0)

- Adapt the Constant Fraction Discriminator (CFD) principle in a pixel when a CFD is paired with a TDC, one time measurement gives the final answer.
- Charge injection and beta source tests consistent with expectation. Tests with beam are planned

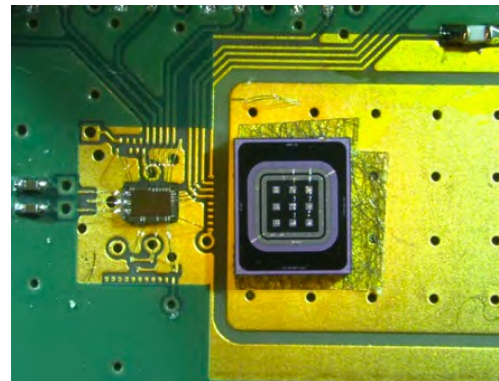


FCFD0

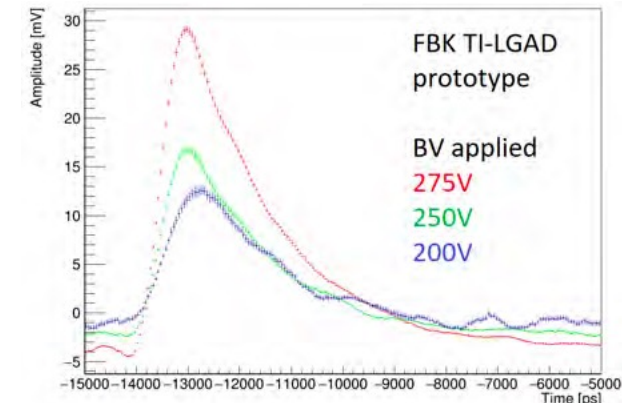


## ASIC Efforts at UC Santa Cruz

| Institution     |       | Technology   | Output         | # of Chan                     | Funding  | Specific Goals        | Status                                  |
|-----------------|-------|--------------|----------------|-------------------------------|----------|-----------------------|---|
| INFN Torino     | FAST  | 110 nm CMOS  | Discrim. & TDC | 20                            | INFN     | Large Capacitance TDC | Testing                                 |
| NALU Scientific | HPSoC | 65 nm CMOS   | Waveform       | 5 (Prototype)<br>> 81 (Final) | DoE SBIR | Digital back-end      | Testing                                 |
| Anadyne Inc     | ASROC | Si-Ge BiCMOS | Discrim.       | 16                            | DoE SBIR | Low Power             | Simulations, final Layout, Board design |



HPSoC



# Funded R&D Activities in FY23

- AC-LGAD Sensor (eRD112)
  - Productions by BNL IO and HPK
  - TCAD simulation, sensor characterization in the lab/beam
- Frontend readout ASIC (eRD109)
  - EICROC0 lab/beam test, EICROC1 submission
  - FCFD0 beam test, FCFD1 submission
  - Characterization of ASICs from 3<sup>rd</sup> party institutions
- Frontend electronics (eRD109)
  - Low-density flexible PCB
- Mechanical structure (eRD112)
  - Light-weight structure made from carbon-fiber composite materials and/or PEEK

**FY23 Deliverables**

- Sensor prototype with 30 ps time and space resolution match RPs and Tracker; Sensor prototype with 20 ps time resolution for ToF.
- 1st sensor + ASIC demonstrator for EIC applications and testing with particle beam.
- 2nd ASIC prototype submissions with better performance and extended features.
- Design and prototype of flexes, interconnects and off-detector electronics.
- Design and prototype of light-weight structure with embedded cooling tubes.



# On-going Work

## R&D [1]

- Sensor
  - BNL, HPK/FBK productions
  - Lab/beam test, Irradiation
- Mechanical structure
  - Low-density mechanical structure
- ASIC:
  - EICROC1, FCFD1, SCIPP
- Frontend electronics
  - Low-mass service hybrid

[1] <https://wiki.bnl.gov/conferences/index.php/ProjectRandDFY23>

[2] <https://wiki.bnl.gov/EPIC/index.php?title=TOFPID>

[3] <https://www.overleaf.com/read/vftxyvjtjrvp>

## Simulation [2]

- DD4HEP geometry, digitization, reconstruction
- Timing resolution requirement
- Spatial resolution requirement
- Material budget requirement

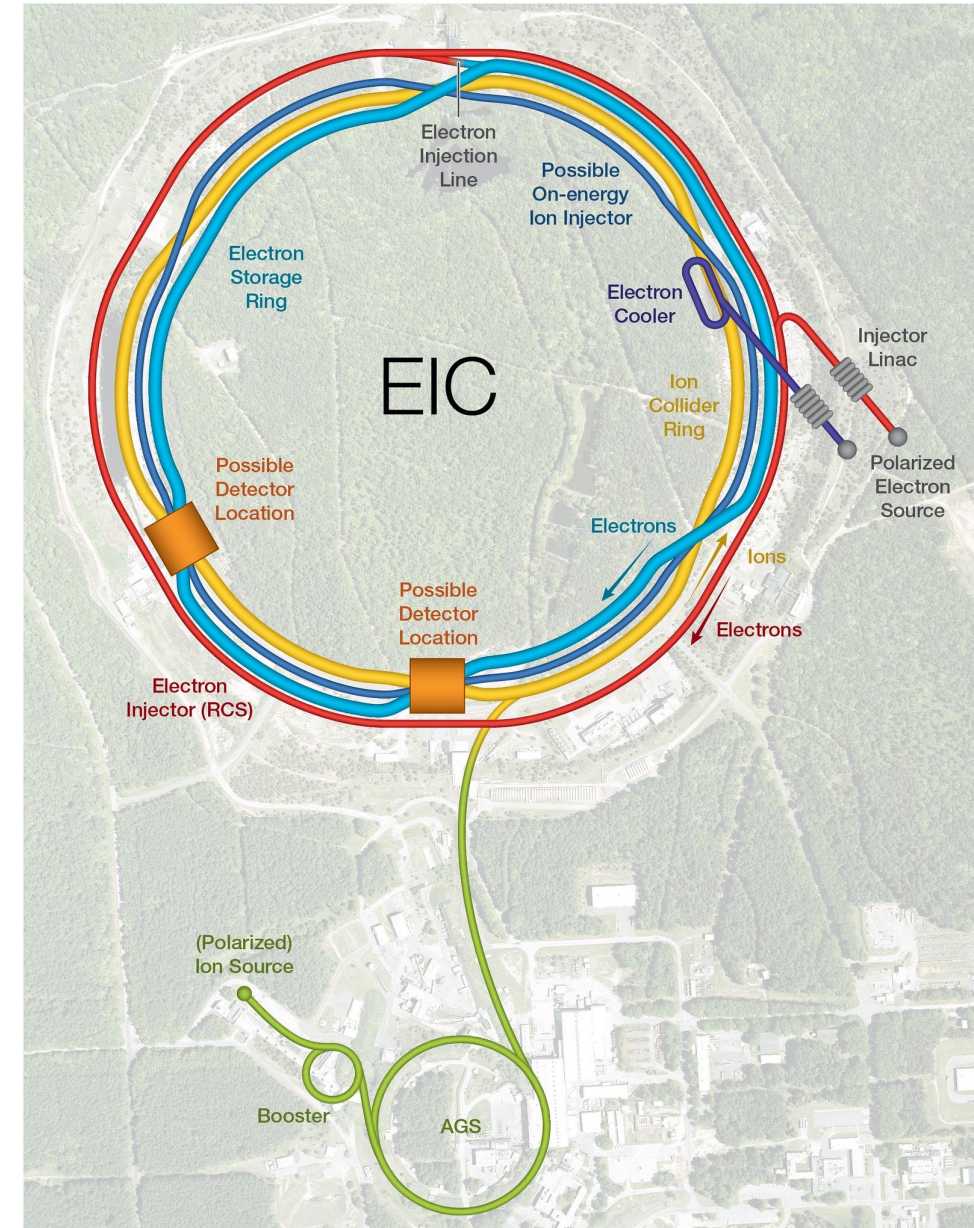
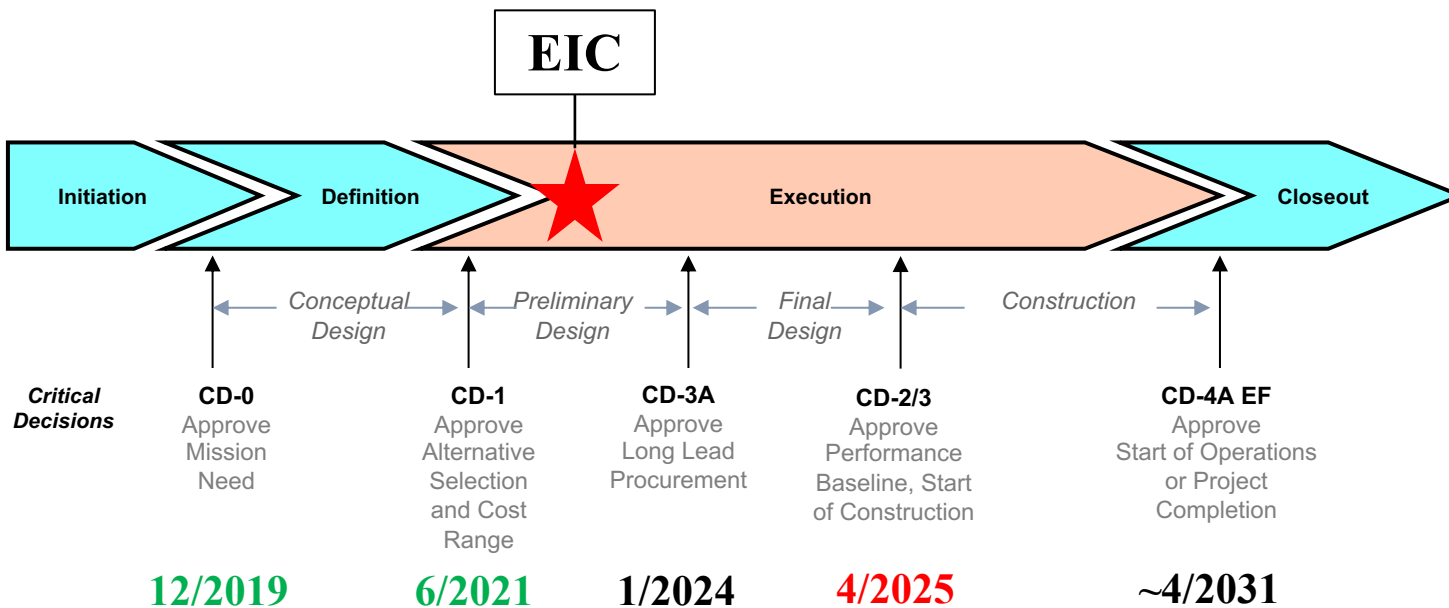
## Project Engineering and Design (PED) [3]

- Mechanical engineering
  - Support structure
  - Cooling system
- Electric engineering – DAQ PED
  - Precision clock distribution (<5 ps)
  - Timing chips and streaming readout
  - Prototype readout board, cables

# Summary and Outlook

**AC-LGAD** is selected by EIC Detector-1 for timing and tracking in central and far-forward detectors.

- Work on-going for detector simulation, R&D and engineering design
- Great opportunity to contribute to the advancement of a 4D tracker technology for future high energy experiments and its first realization at EIC



**Electron Beam: 5-18 GeV Ion: 40, 100-275 GeV**



# References

- [1] Electron Ion Collider: The Next QCD Frontier - Understanding the glue that binds us all (2012), [arXiv:1212.1701](#)
- [2] Reaching for the Horizon: The 2015 Long Range Plan for Nuclear Science (2015), [link](#)
- [3] An Assessment of U.S.-based Electron-Ion Collider Science (2018), [link](#)
- [4] Electron Ion Collider Conceptual Design Report (2021), [link](#)
- [5] Science Requirements and Detector Concepts for the Electron-Ion Collider: EIC Yellow Report, [arXiv:2103.05419](#)
- [6] EIC Detector Proposals and Advisory Panel Report (2022), [link](#)
- [7] eRD112: EIC AC LGAD R&D Proposal (2022), [link](#)

